OFC 2022: EV Group and Teramount developing packaging tech for PICs – iMicronews) – March 11, 2022

The Challenge of Getting to Zero Carbon Emissions

Getting to zero carbon emissions will be a significant challenge for the semiconductor industry. With the industry expected to grow at a 7.1% CAGR through 2026 according to IC Insights, and units reaching 1.15 trillion in 2021 according to the SIA, reducing energy consumption and greenhouse gas (GHG) emissions will cause more than one vice president in charge of curtailing GHG emissions to lose sleep.

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TODAY!

A 3D-IC includes the package, interposer, multiple chiplets, TSVS and TDVs. Supplying power to the chiplets and dissipating heat through these various components poses major power and thermal integrity challenges. Early analysis also is extremely critical in 3D-ICs since changing the die stack up later in the design process is challenging or not possible. In this session, get a chip-centric perspective on how to perform PI and thermal integrity analysis in 3D-ICs from early planning to signoff.

LEARN MORE

3D InCites Yearbook Editorial: Keeping Up with the Times

READ POST

IFTLE 513: The IPC NA Advanced Packaging Ecosystem Gap Assessment

READ POST

Introducing SurplusGLOBAL

WATCH VIDEO

From The Archives: Meeting Sustainability Development Goals through an Effective ESG Strategy

LISTEN TO PODCAST

Member of the Week

Welcome one of our newest members MRSI Mycronic. MRSI Systems (Mycronic Group) is a leading manufacturer of fully automated, high-speed, high-precision and flexible eutectic and epoxy die bonding systems. MRSI provides die bonders with accuracy from 5 microns to 0.5 microns with industry leading high flexibility for true multi-die, multi-process production. Its solutions are used for research and development, low-to-medium volume production, and high-volume manufacturing of photonic devices, RF and microwave devices, electronic components, MEMS devices and sensors. Its flagship product, the MRSI-HVM 1.5 micron high-speed die bonder, meets the needs of many industries from telecom, datacom and medical devices manufacturers to most commercial sectors. Key Benefits include dual gantry/head design for industry leading high speed for high volume manufacturing; high accuracy to optimize yield and achieve high density packaging; and industry leading high flexibility for true multi-die multi-process production.

LEAN MORE

Company News

Finetech USA Adds Clean Room Space to its Customer Applications Center

Panel-Level debonding solutions from ERS – An interview by i-Micronews

OFC 2022: EV Group and Teramount developing packaging tech for PICs – iMicronews

Recommended Reads

Net-Zero by 2050 – A Roadmap for the Global Energy Sector – Semiconductor Digest

Events

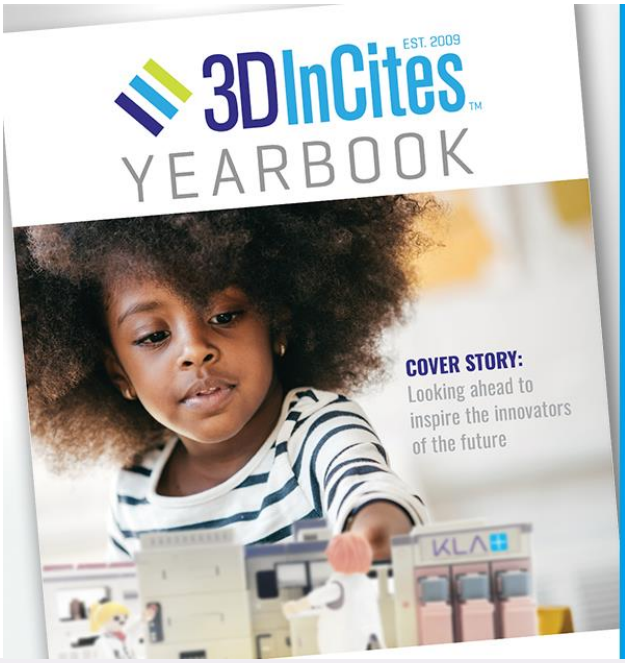
DATE 2022 Friday Workshop on "3D Integration: Heterogeneous 3D Architectures and Sensors"
March 18, 2022

Webinar Series: 3D-IC Chip-Centric Power/Thermal Integrity with High-Performance Hierarchical Analysis
March 23, 2022

SEMI Industry Strategy Symposium (ISS) 2022 | Live Event
April 3-6, 2022

Call for Papers

2022 International Test Conference: Deadline March 14



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